



Event Advisory: Semiconductor Industry Leaders to Examine the Future of Interconnects at December 11th Event

December 3, 2012

SANTA CLARA, Calif., December 3, 2012 - The 14 nanometer node is expected to be an inflection point for the chip industry, beyond which the resistivity of copper interconnects will increase exponentially and may become a limiting factor in chip design. On December 11, 2012, Applied Materials, Inc. will host an important forum in San Francisco to explore the path that interconnect technology must take to keep pace with transistor scaling and the transition to new 3D architectures.

The discussion will address critical questions for the semiconductor industry, including the possibility of replacing copper as the material of choice for interconnect structures. If not, will new circuit designs and system architectures be able to address future limitations in interconnect performance? The complexity of multi-patterning and EUV timing may also impact chipmakers' interconnect pitch scaling roadmaps.

Guest speakers from across the industry will provide insights on these critical issues in a panel titled "Interconnect Performance - Overcoming the Impact of Transistor Scaling." To register for this exceptional event, please visit www.appliedmaterials.com/interconnect-panel.

Introduction: Klaus Schuegraf, Ph.D. Vice president and chief technology officer, Silicon Systems Group, Applied Materials, Inc.

Panel: Robert Aitken, Ph.D. Fellow, ARM Holdings, Ltd.
Jon Candelaria Director, interconnect and packaging sciences, Semiconductor Research Corp.
Dinesh Somasekhar, Ph.D. Senior scientist, Intel Corp.
Zsolt Tokei, Ph.D. Program director, nano interconnects, IMEC
Mehul Naik, Ph.D. Distinguished member of technical staff, Applied Materials, Inc.
Douglas Yu, Ph.D. Senior director, backend R&D, TSMC, Ltd.
David Lammers (moderator) Contributing editor, SemiMD.com

Where: Hotel Nikko
222 Mason Street, San Francisco, CA 94102

When: Tuesday, December 11, 2012

Schedule: 5:00pm - 6:15pm Registration and Reception
6:15pm - 7:40pm Panel Discussion
7:40pm - 8:00pm Beverages/Social

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